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MARKED VERSION TO SHOW CHANGES

- 4. (amended) The photoresist of <u>claim 1</u> [any one of claims 1 through 3] wherein the carbon alicyclic group is a polymerized norbornene group.
- 5. (amended) The photoresist of <u>claim 1</u> [any one of claims 1 through 4] wherein the heteroalicyclic group has a non-hydrogen ring substituent.
- 8. (amended) The photoresist of <u>claim 1</u> [claim 7] wherein the polymer comprises a polymerized acrylate that comprises a photoacid-labile moiety.
- 13. (amended) The photoresist of <u>claim 1</u> [any one of claims 1 through 11] wherein the heteroalicyclic group fused to the polymer backbone is not an anhydride or lactone.
- 23. (amended) The photoresist of <u>claim 1</u> [any one of claims 1 through 22] wherein the polymer is a tetrapolymer or a pentapolymer.
- 24. (amended) The photoresist of <u>claim 1</u> [any one of claims 1 through 23] wherein the polymer is completely free of aromatic groups.
- 35. (amended) A method of forming a positive photoresist relief image, comprising:
- (a) applying a coating layer of a photoresist of <u>claim 1</u> [any one of claims 1 through 24] on a substrate; and
 - (b) exposing and developing the photoresist layer to yield a relief image.
- 41. (amended) An article of manufacture comprising a microelectronic wafer substrate or flat panel display substrate having coated thereon a layer of the photoresist composition of <u>claim 1</u> [any one of claims 1 through 24].